

MOSFETs Silicon N-channel MOS (U-MOSIX-H)

# TPWR8004PL

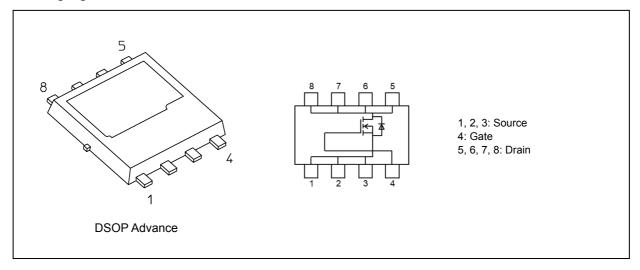
### 1. Applications

- · High-Efficiency DC-DC Converters
- · Switching Voltage Regulators
- · Motor Drivers

#### 2. Features

- (1) High-speed switching
- (2) Small gate charge:  $Q_{SW} = 23 \text{ nC (typ.)}$
- (3) Small output charge:  $Q_{oss} = 85.4 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 0.65 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (5) Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 40 \text{ V)}$
- (6) Enhancement mode:  $V_{th} = 1.4 \text{ to } 2.4 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 1.0 \text{ mA})$

### 3. Packaging and Internal Circuit





### 4. Absolute Maximum Ratings (Note) (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristi	cs		Symbol	Rating	Unit
Drain-source voltage			$V_{DSS}$	40	V
Gate-source voltage			$V_{GSS}$	±20	
Drain current (DC)	(T <sub>c</sub> = 25 °C) (Bottom drain)	(Note 1), (Note 2)	I <sub>D</sub>	150	Α
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I <sub>D</sub>	340	Α
Drain current (pulsed)	(t = 100 μs)	(Note 1)	I <sub>DP</sub>	500	Α
Power dissipation	(T <sub>c</sub> = 25 °C) (Bottom drain)		$P_D$	170	W
Power dissipation		(Note 3)	$P_{D}$	3.0	W
Power dissipation		(Note 4)	P <sub>D</sub>	1.0	W
Single-pulse avalanche energy		(Note 5)	E <sub>AS</sub>	336	mJ
Single-pulse avalanche current		(Note 5)	I <sub>AS</sub>	120	Α
Channel temperature			T <sub>ch</sub>	175	°C
Storage temperature			T <sub>stg</sub>	-55 to 175	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

Characteristic	Symbol	Max	Unit		
Channel-to-case thermal resistance	Bottom drain (T <sub>c</sub> = 25 °C)		R <sub>th(ch-c)</sub>	0.88	°C/W
Channel-to-case thermal resistance	Top source (T <sub>c</sub> = 25 °C)		R <sub>th(ch-c)</sub>	0.93	°C/W
Channel-to-ambient thermal resistance	(T <sub>a</sub> = 25 °C)	(Note 3)	R <sub>th(ch-a)</sub>	50	°C/W
Channel-to-ambient thermal resistance	(T <sub>a</sub> = 25 °C)	(Note 4)	R <sub>th(ch-a)</sub>	142	°C/W

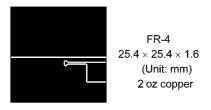
Note 1: Ensure that the channel temperature does not exceed 175 °C.

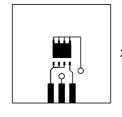
Note 2: Limited by package limit. Silicon chip capability is 340 A. ( $T_c = 25$  °C)(Bottom drain)

Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5:  $V_{DD}$  = 32 V,  $T_{ch}$  = 25 °C (initial), L = 18  $\mu$ H,  $I_{AS}$  = 120 A





FR-4 25.4 × 25.4 × 1.6 (Unit: mm) 2 oz copper

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μА
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	_	_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	40	_	_	V
	V <sub>(BR)DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	25	_	_	
Gate threshold voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1.0 mA	1.4	_	2.4	
Drain-source on-resistance	R <sub>DS(ON)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$	_	0.95	1.35	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A	_	0.65	0.80	

## 6.2. Dynamic Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	7370	9600	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	58		
Output capacitance	C <sub>oss</sub>		_	1930		
Gate resistance	r <sub>g</sub>	_		0.6	1.1	Ω
Switching time (rise time)	t <sub>r</sub>	See Fig. 6.2.1		13		ns
Switching time (turn-on time)	t <sub>on</sub>			26		
Switching time (fall time)	t <sub>f</sub>		_	14	_	
Switching time (turn-off time)	t <sub>off</sub>		_	63	_	

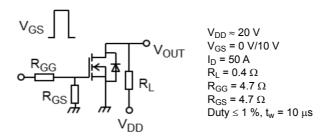


Fig. 6.2.1 Switching Time Test Circuit

## 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	$Q_g$	$V_{DD} \approx 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$	_	103	_	nC
gate-drain)		$V_{DD} \approx 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$	_	49	_	
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$	_	25	_	
Gate-drain charge	$Q_{gd}$		_	12.4	_	
Gate switch charge	$Q_{SW}$		_	23	_	
Output charge	Q <sub>oss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	_	85.4	_	

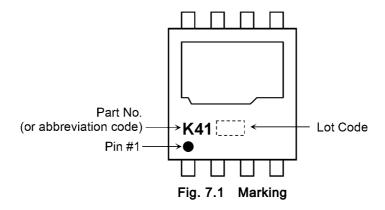


## 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note 6)	I <sub>DRP</sub> (t = 100 μs)	_	1	ı	500	Α
Diode forward voltage	$V_{DSF}$	I <sub>DR</sub> = 150 A, V <sub>GS</sub> = 0 V	1		-1.2	V
Reverse recovery time		$V_R = 20 \text{ V}, I_{DR} = 37.5 \text{ A}, V_{GS} =$		58		ns
Reverse recovery charge	Q <sub>rr</sub>	0 V, -dI <sub>DR</sub> /dt = 100 A/μs		70	_	nC

Note 6: Ensure that the channel temperature does not exceed 175 °C.

### 7. Marking



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### 8. Characteristics Curves (Note)

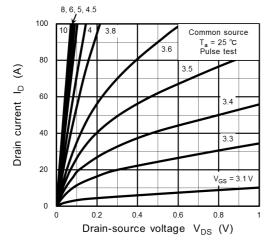


Fig. 8.1 I<sub>D</sub> - V<sub>DS</sub>

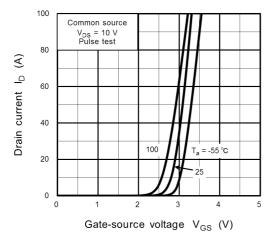


Fig. 8.3 I<sub>D</sub> - V<sub>GS</sub>

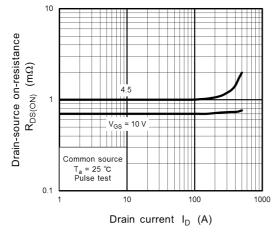


Fig. 8.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

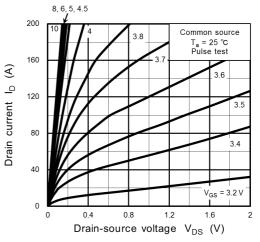


Fig. 8.2 I<sub>D</sub> - V<sub>DS</sub>

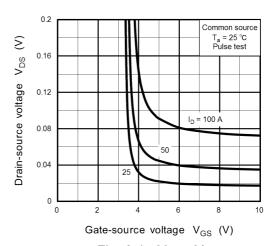


Fig. 8.4 VDS - VGS

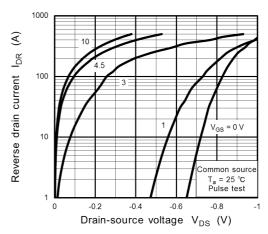


Fig. 8.6 IDR - VDS



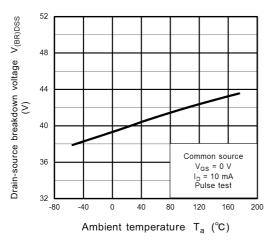


Fig. 8.7 V<sub>(BR)DSS</sub> - T<sub>a</sub>

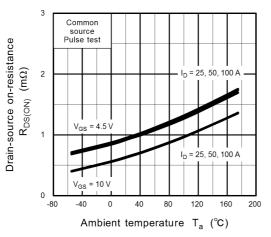


Fig. 8.9 R<sub>DS(ON)</sub> - T<sub>a</sub>

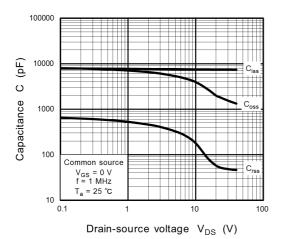


Fig. 8.11 Capacitance - V<sub>DS</sub>

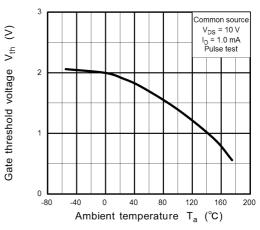


Fig. 8.8 V<sub>th</sub> - T<sub>a</sub>

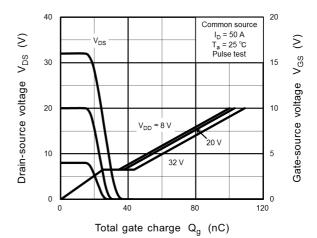


Fig. 8.10 Dynamic Input/Output Characteristics

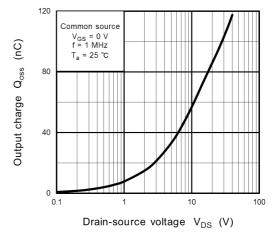


Fig. 8.12 Q<sub>oss</sub> - V<sub>DS</sub>



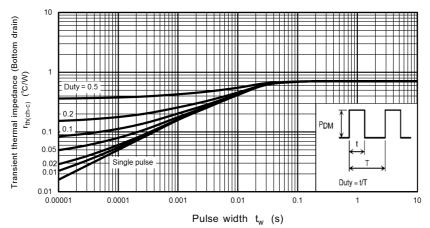


Fig. 8.13 r<sub>th</sub> - t<sub>w</sub> (Bottom drain) (Guaranteed Maximum)

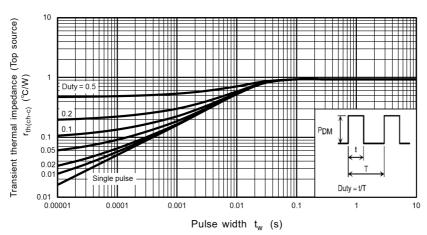


Fig. 8.14  $r_{th}$  -  $t_w$  (Top source) (Guaranteed Maximum)

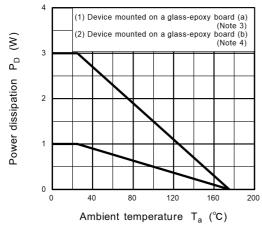


Fig. 8.15 P<sub>D</sub> - T<sub>a</sub> (Guaranteed Maximum)

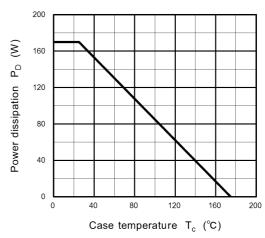


Fig. 8.16 P<sub>D</sub> - T<sub>c</sub> (Bottom drain) (Guaranteed Maximum)



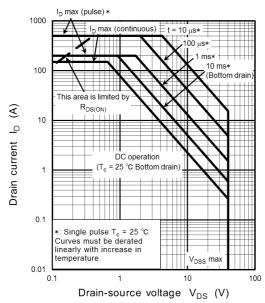


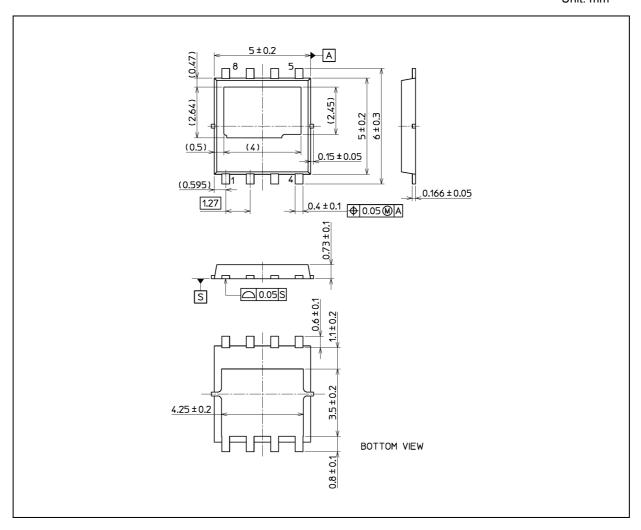
Fig. 8.17 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



### **Package Dimensions**

Unit: mm



Weight: 0.104 g (typ.)

Package Name(s)
TOSHIBA: 2-5S1A
Nickname: DSOP Advance



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